

REMARKS

The above amendment to the claims has been made to incorporate the amendment made in response to the international preliminary examination and to remove improper multiple dependent claims.

Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page is captioned "Version with Markings to Show Changes Made."

In the event that any fees are due in connection with this paper, please charge our Deposit Account No. 01-2340.

Respectfully submitted,

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE SPECIFICATION:

Paragraph beginning at page 1, line 6 is amended as follows:

The present invention relates to a method of uniformly applying [a liquid material, such as] a paste, on the surface of a metal piece.

Paragraph beginning at page 1, line 8 is amended as follows:

The term "paste" used in the present invention means a [liquid material] paste, e.g., an adhesive and paint, which has such a level of viscosity as allowing the liquid material to be laid on the paste-applied surface in the linear form. One example of the liquid material is a thermosetting conductive resin.

Paragraph beginning at page 2, line 11 is amended as follows:

An object of the present invention is to provide a paste pad forming method which can apply [a liquid material, such as] a paste, with much less variations in liquid amount than resulted by the prior-art method of arranging a number of nozzles in a desired drawing pattern for multi-dot coating, and which can completely prevent a bubble from being entrapped in a step of bonding a bonded member, e.g., a semiconductor chip, to a paste-applied body, e.g., a lead frame, through the applied [liquid material] paste.

IN THE CLAIMS:

Claims 1, 4-6, 8, 9 and 11-13 have been amended as follows:

1. A paste pattern forming method wherein a drawing pattern is formed on a paste-applied body with a linearly drawn paste line such that no bubbles are left in joining surfaces when the joining surfaces are bonded to each other.

4. A paste pattern forming method according to claim 2 [or 3], wherein the paste line is drawn while moving any of said paste-applied body, said nozzle and said paste.

5. A paste pattern forming method according to [any one of Claims 1 to 4] claim 1 or 2, wherein said paste-applied body is a lead frame, and said paste is an adhesive for die bonding.

6. A paste pattern forming method according to [any one of Claims 1 to 5] claim 1 or 2, wherein said drawing pattern is a figure made up of a plurality of segment lines.

8. A paste pattern forming method according to [any one of Claims 1 to 6] claim 1 or 2, wherein said drawing pattern is a figure including an enclosed shape.

9. A paste pattern forming method according to [any one of Claims 6 to 8] claim 6, wherein at least one segment line is formed of two drawn lines.

11. A paste pattern forming method according to [any one of Claims 1 to 10] claim 1 or 2, wherein said drawing pattern is formed such that the total number of start and end points of drawn lines is not larger than the number of segment lines.

12. A paste pattern forming method according to [any one of Claims 1 to 11] claim 1 or 2, wherein said drawing pattern is formed such that the start and end points of drawn lines are positioned other than the ends of said drawing pattern.

13. A paste pattern forming method according to [any one of Claims 1 to 12] claim 1 or 2, wherein said drawing pattern is formed with a minimum number of points at which the drawn lines are returned in a drawing process.

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